

The Photon Science Detector Group

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DESY

- **Now:** DORIS; 2nd generation SR; 37 stations
- **Now:** FLASH; shortest λ FEL; 5 stations
- **Now:** part of ESRF
- **+3 years:** PETRA-3; high brilliance SR
- **+3 years:** access to LCLS
- **+6 years:** European XFEL next door

- Develop a strong **PS Detector-group**
- Give **support** to Storage Rings
- Take a **major role** in the XFEL photon detector developments
- Utilize all **competences** and resources available **at DESY**
- Strive for **synergy** Photon Science - HEP

BL1	Inelastic X-ray Scattering	<i>12 (18) cell SDD, pnsensor</i>	$d \approx 3\text{cm}$	1x1	
	Pico Second Science	<i>Streak camera C5680, HAMAMATSU</i>			
BL2	High Resolution Diffraction	<i>Cyberstar NaI, Oxford danfysik</i>		1x1	
		<i>Cyberstar YAP, Oxford danfysik</i>		1x1	
		<i>APD complete system, Oxford danfysik</i>		1x1	
		<i>single cell SDD, pnsensor</i>	$d \approx 6\text{mm}$	1x1	
		<i>detecting scattered radiation from a foil</i>	$8 \times 8\text{mm}^2$		
		<i>CCD: PI-SCX 4096, Roper Scientific (4x4 binning)</i>	$60 \times 60\mu\text{m}^2$	1kx1k	1 s
BL3	$\mu\text{SAXS} / \text{WAXS}$	<i>CCD: PI-SCX 4096, Roper Scientific (2.5:1 taper)</i>	$38 \times 38\mu\text{m}^2$	4kx4k	4.5 s
		<i>pnCCD</i>	$51 \times 51\mu\text{m}^2$	256×256	1 ms
BL5					
BL6	$\mu\text{X-Ray Fluorescence}$	<i>Si(Li), e2v scientific instruments</i>	80mm^2	1x1	
	X-ray Absorption Spectroscopy	<i>Si, radiant</i>	50mm^2	1x1	
	EXAFS	<i>HPGe, e2v scientific instruments</i>	30mm^2	1x1	
	$\mu\text{diffraction}$	<i>CCD: PI-SCX 4096, Roper Scientific (4x4 binning)</i>	$114 \times 114\mu\text{m}^2$	1kx1k	1 s
	$\mu\text{Tomography}$	<i>FReLoN-camera 2k14, ESRF</i>	$0.5 \times 0.5\mu\text{m}^2$	1kx1k	8fps
BL7					
BL8	Resonance Scattering	<i>single cell SDD, pnsensor</i>	$d \approx 6\text{mm}$	1x1	
		<i>pnCCD with scintillator</i>	$75 \times 75\mu\text{m}^2$	1kx1k	1 s
BL10	X-ray Photon Correlation Spectroscopy	<i>single cell SDD, pnsensor</i>	$d \approx 6\text{mm}$	1x1	10 μs
		<i>MCAT gaseous detector</i>	$<300 \times 300\mu\text{m}$	1kx1k	<10 ms



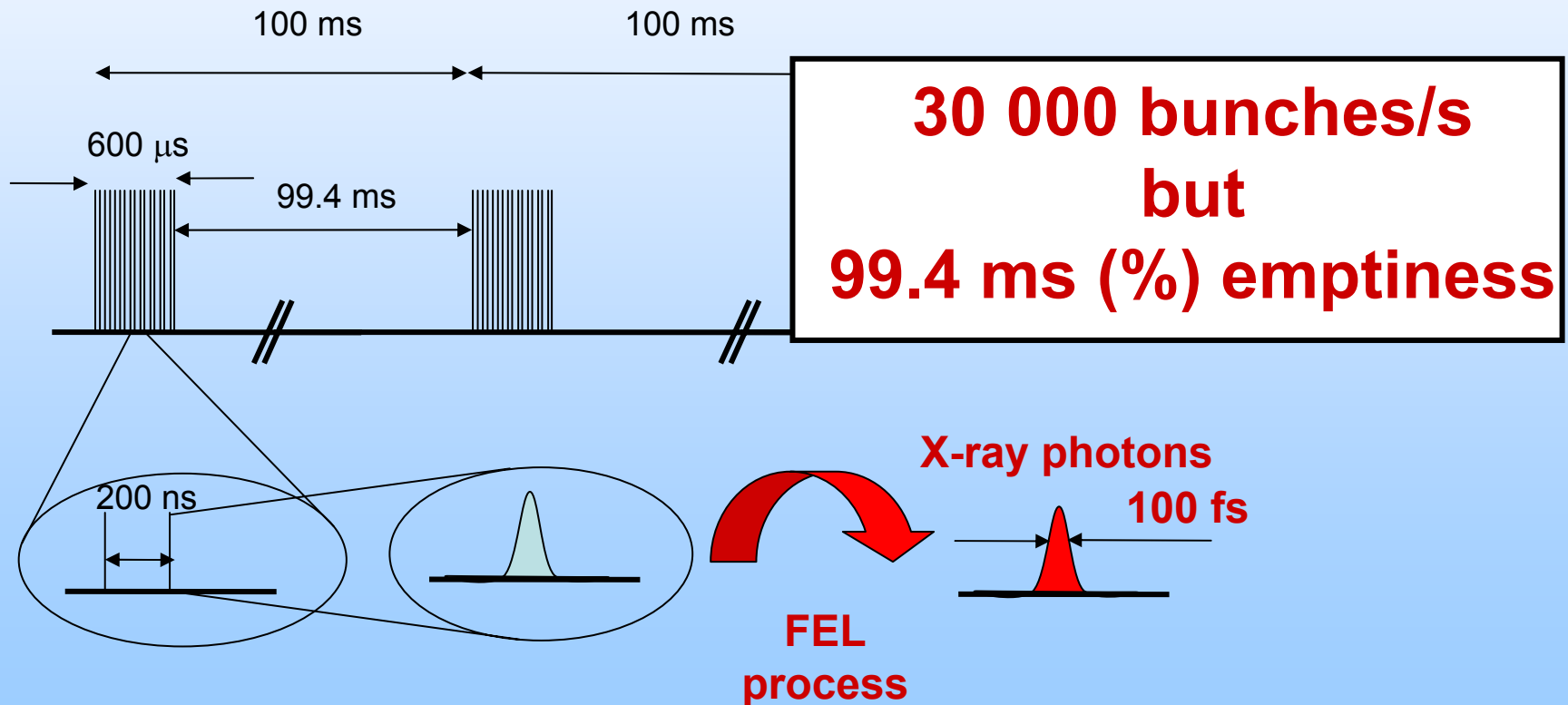
- New **Roper Scientific CCD** camera ordered and waiting delivery.
- **PILATUS 100K** modules received and tested
- Collaboration on **MYTHEN strip** detector (6-10 MYTHEN, plus new integrating chip; Q1 2007)
- Joined **Medipix-3** collaboration
- Test of **pnCCD** in early 2007 at FLASH, if successful consider also for PETRA-III
- APD-array and Diamonds still in start-up phase

Developments driven by XFEL project

spin-off to
other sources

Time structure: difference with “others”

Electron bunch trains; up to 3000 bunches in 600 μs , repeated 10 times per second.
Producing 100 fsec X-ray pulses (up to 30 000 bunches per second).

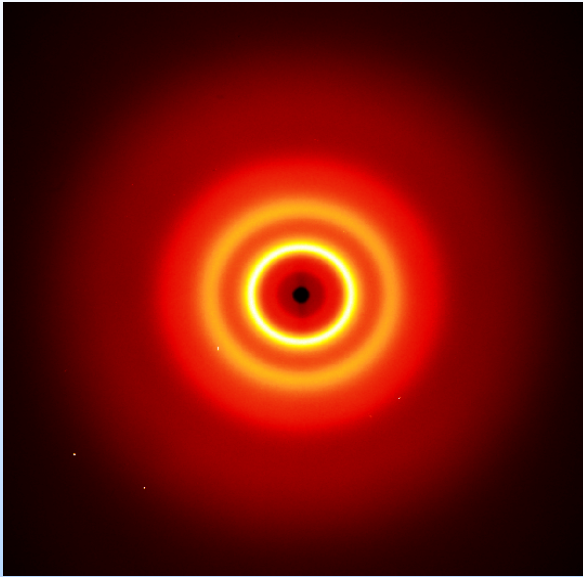


- Either: $< 10\text{Hz}$ or $> 1.5\text{ kHz}$; best 5 MHz
- All photons arrive in 100 fsec →
integrating detectors.
- Experiments should profit from high luminosity ($30\ 000\text{ shots/sec}$).
- **Every shot is a new experiment** (jitter, sample destruction,..)

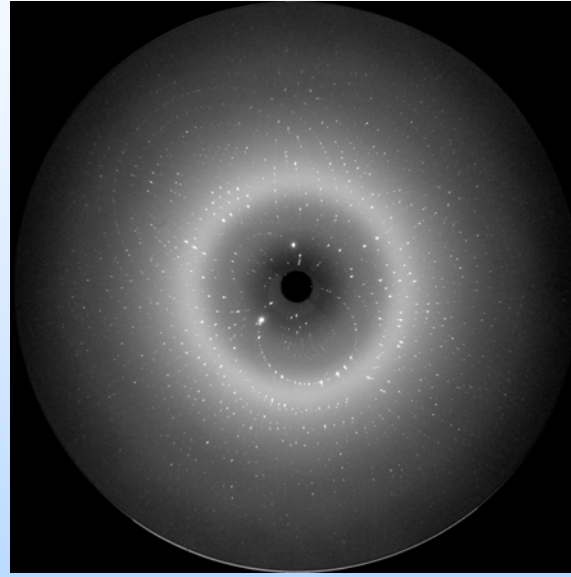
What are the different needs?

Different detectors are needed and are foreseen:

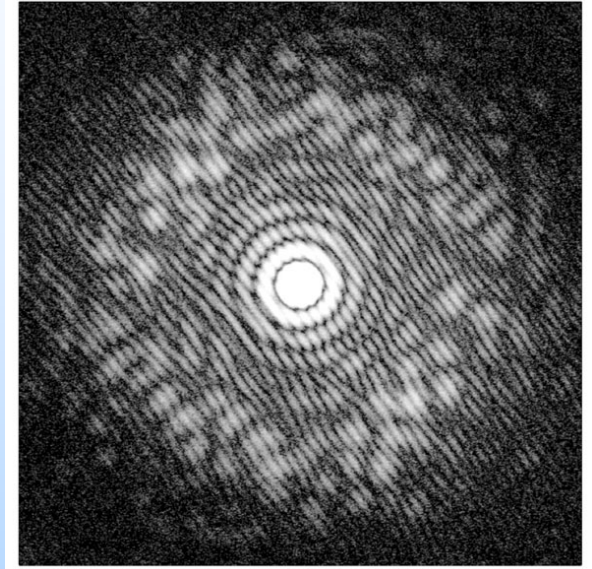
- X-ray Streak Cameras: **Coming out today!**
- Particle detectors
- 0D/1D detectors
- **2D X-ray detectors:**
 - **Single Particle Imaging**
 - **Coherent Diffraction Imaging**
 - **X-ray Photon Correlation Spectroscopy**
 - **Pump-Probe non-crystalline diffraction**
 - **Pump Probe crystalline diffraction**



Liquids



Crystals



Particles

**17th July 2006:
46 pages;
covering 5 areas**

**6 Eols received;
different consortia
and technologies**

**3 Eols selected to
develop full
proposal**



Call by the:

**European Project Team for the
X-ray Free-Electron Laser**

for:

Expressions of Interest

to:

**Develop and Deliver
Large Area Pixellated X-ray
Detectors.**

Deadline: 30 September 2006
<http://xfel.desy.de/xfelhomepage>

Replies to the Call for Expression of Interest

Eol No.	Submitted by	Subject
XFEL Detectors Eol-01	Advanced Study Group of MPG, DESY, University of Siegen	The fully depleted, back-illuminated high speed, large format X-ray pnCCD
XFEL Detectors Eol-02	Advanced Study Group of the Max-Planck Gesellschaft, DESY, the IHP (FFO), the University of Mannheim, the University of Siegen, the Politecnico di Milano/INFN and PNsensor	Large Format X-ray Imager with Mega-Frame Readout Capability based on a Linear Silicon Drift Detector (LSDD)
XFEL Detectors Eol-03	[REDACTED]	GaAs and Si detectors with CMOS readout for the XFEL
XFEL Detectors Eol-04	CCLRC	CCLRC Large Pixel Detector
XFEL Detectors Eol-05	The DESY/PSI/UniBonn/UniHamburg consortium	The Analogue Pipe-Line Hybrid Pixel Array Detector
XFEL Detectors Eol-06	[REDACTED]	Large Area Pixellated X-ray Detectors, Single Particles and Biomolecules (SPB)

Diode Detection Layer

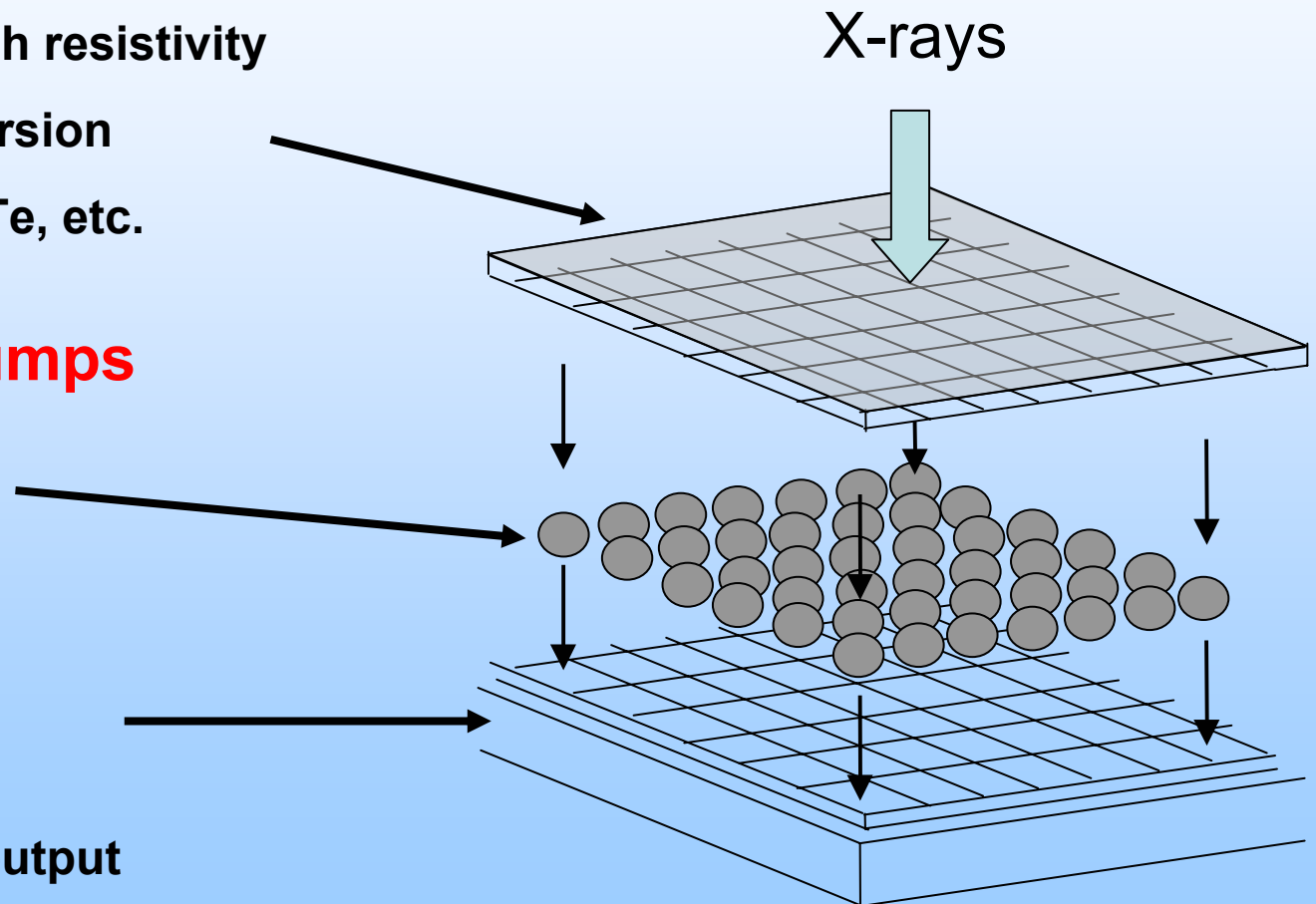
- Fully depleted, high resistivity
- Direct x-ray conversion
- Silicon, GaAs, CdTe, etc.

Connecting Bumps

- Solder or indium
- 1 per pixel

CMOS Layer

- Signal processing
- Signal storage & output



Gives enormous flexibility!

Analog Pipeline Pixel Chip

Basic idea:

- Integrating system
- Configurable analog frontend
- Store images of micro-bunches on caps in the pixels (5MHz switching)
- Readout the images during the 100ms gap

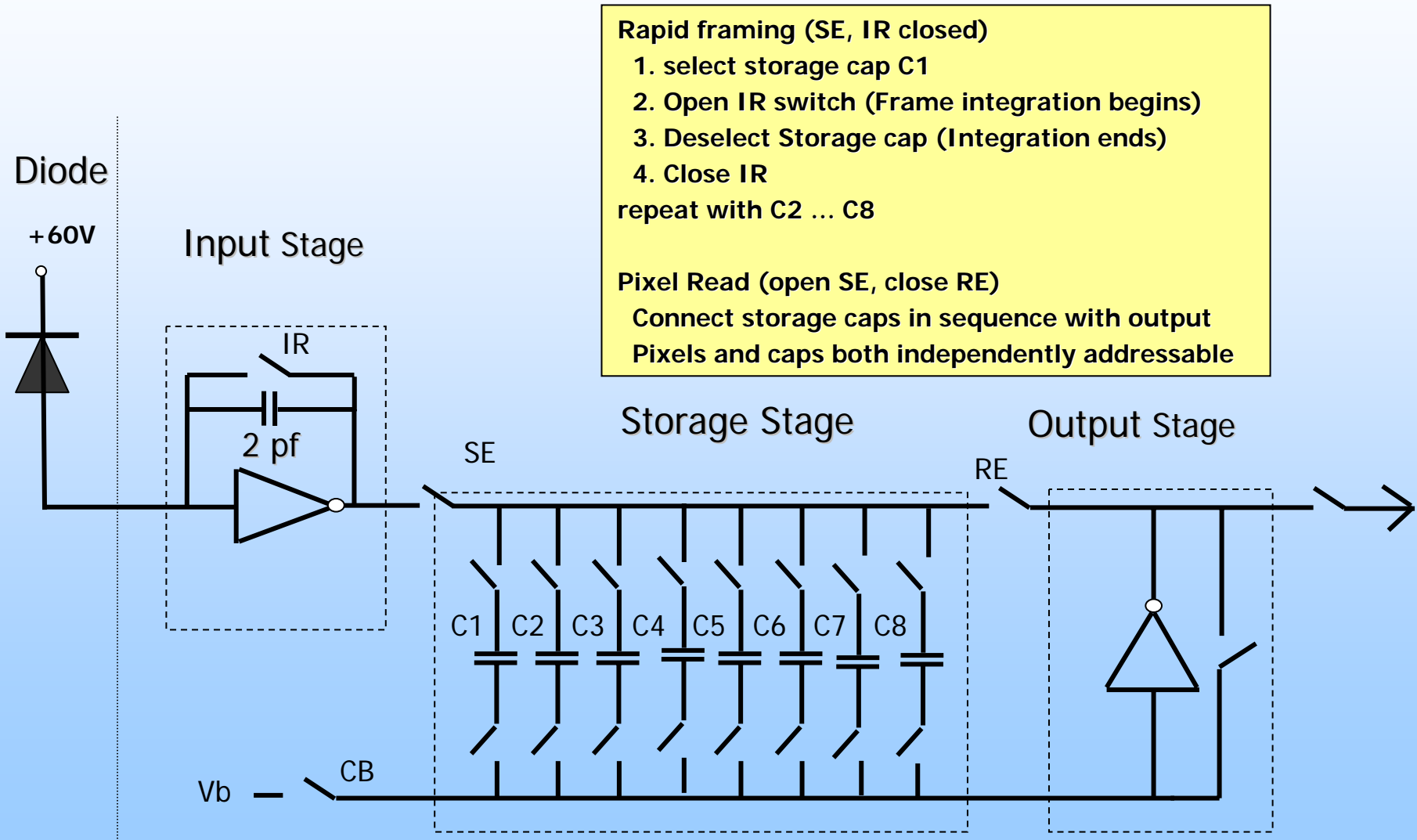
Predecessor Chips:

HEP: H1 strip Analog Pipeline Chip (APC), CMS & Atlas strip and others

X-ray Pixel: APAD Cornell

We do not start from scratch

...



Gasoline fuel injector spray

Courtesy Sol Gruner

X-ray beam

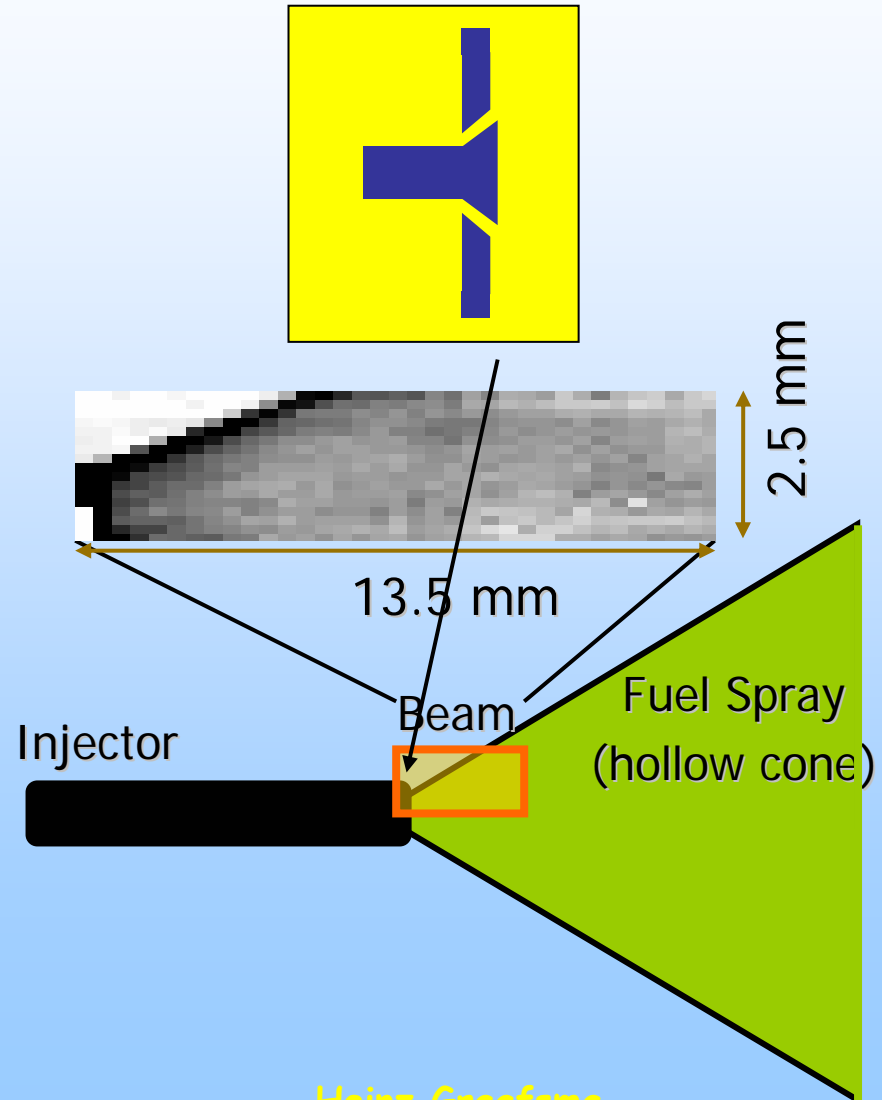
- CHESS Beamline D-1
- 6 keV (1% bandpass)
- 2.5 mm x 13.5 mm
- (step sample to tile large area)
- 10^9 x-rays/pix/s
- 5.13 μ s integration (2x ring period)

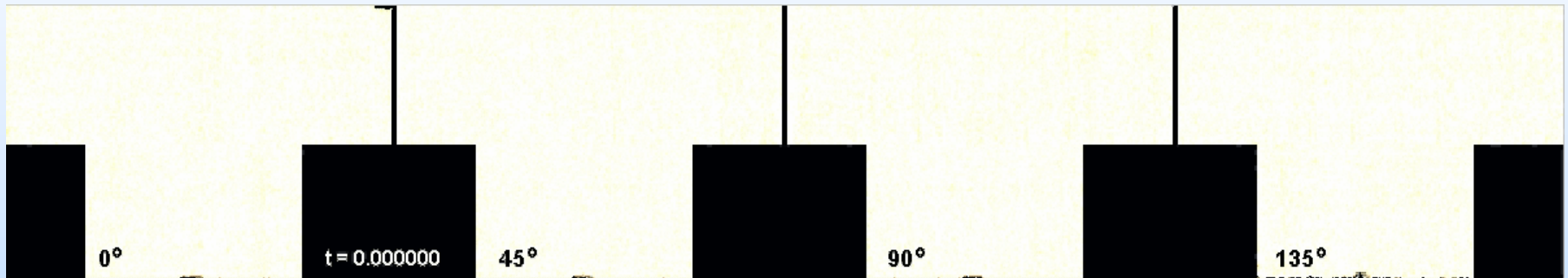
Fuel injection system

- Cerium added for x-ray contrast
- 1000 PSI gas driven
- 1 ms pulse
- 1 ATM Nitrogen

Collaboration: Jin Wang (APS) & S.M. Gruner (Cornell)

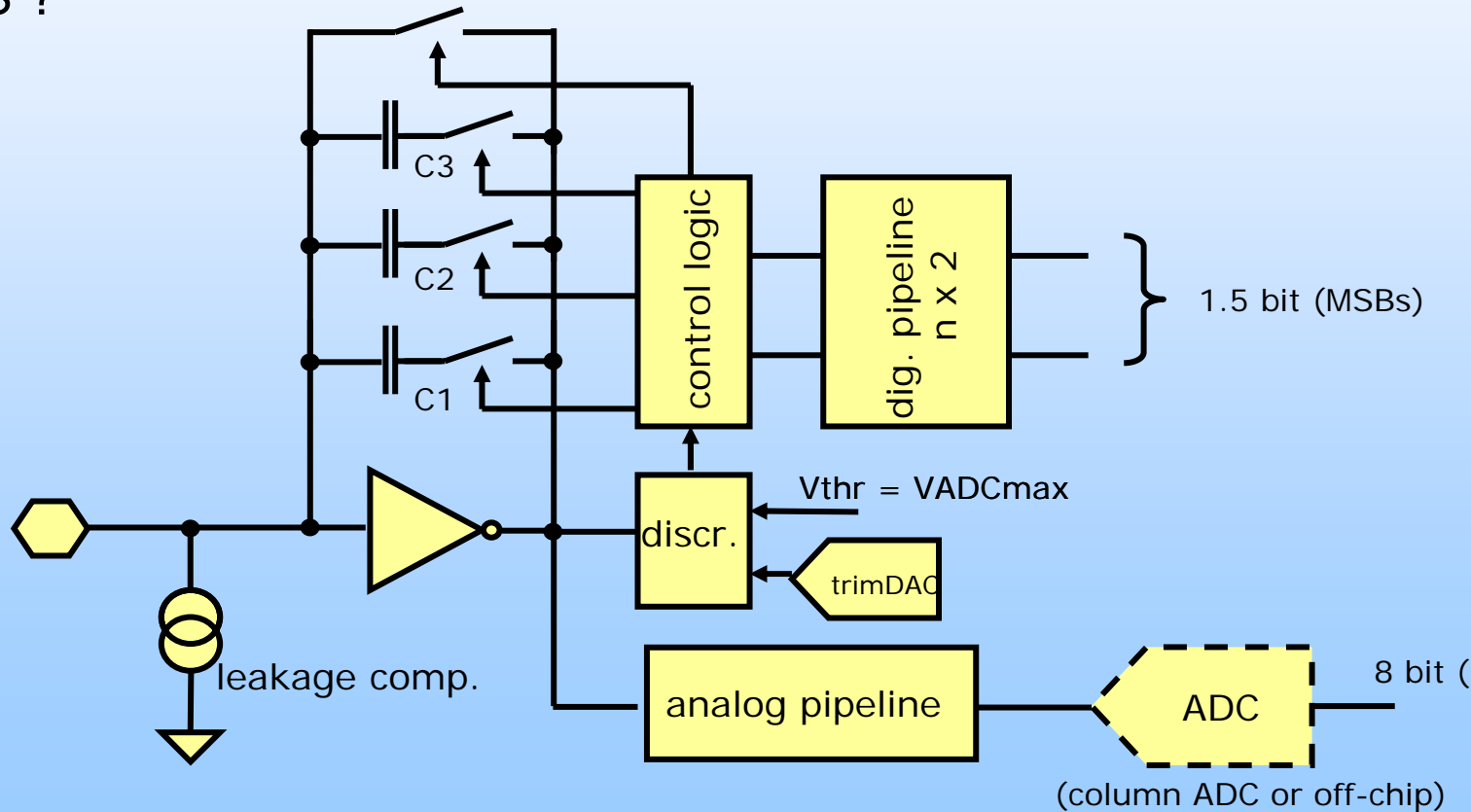
See: Cai, Powell, Yue, Narayanan, Wang, Tate, Renzi, Ercan, Fontes & Gruner
Appl. Phys. Lett. 83 (2003) 1671.



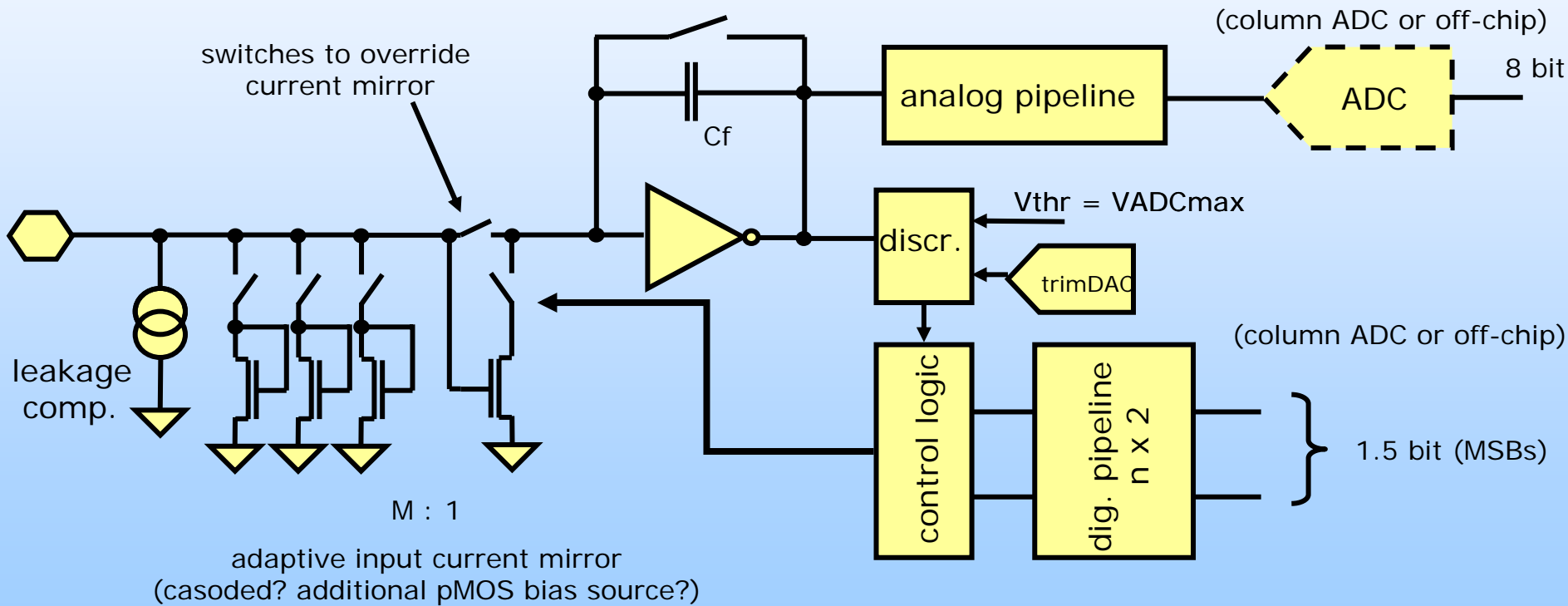


- 1.8 ms time sequence (composite). 10^5 images
- $5.13 \mu\text{s}$ exposure time. ($15.4 \mu\text{s}$ between frames)
- 88 frames (11 groups of 8 frames), Avg. 20x for noise.
- 1000 x-rays/pixel/ μs
- Data taken with 4 projections.

- wide dynamic input range
- multiple (3) scaled feedback capacitors
- reduced ADC resolution (8 bit instead of 10 bit)
- analog + digital (2 bit) pipeline
- in-pixel CDS ?



- keep C_f fixed
- scale input current with configurable current mirror: $M_i = 1, 16, 64 \dots$
- increase dynamic range beyond 10^4 ($i > 3$)
- could be implemented in less area



Rough dimensions:

~ 20 μm^2 / cap cell ->

1000 caps (frames) ~ 140 x 140 μm^2 -> Pixel size ~ 160 x 160 μm^2

500 caps (frames) ~ 100 x 100 μm^2 -> Pixel size ~ 120 x 120 μm^2

100 caps (frames) ~ 44 x 44 μm^2 -> Pixel size ~ 65 x 65 μm^2

Readout system:

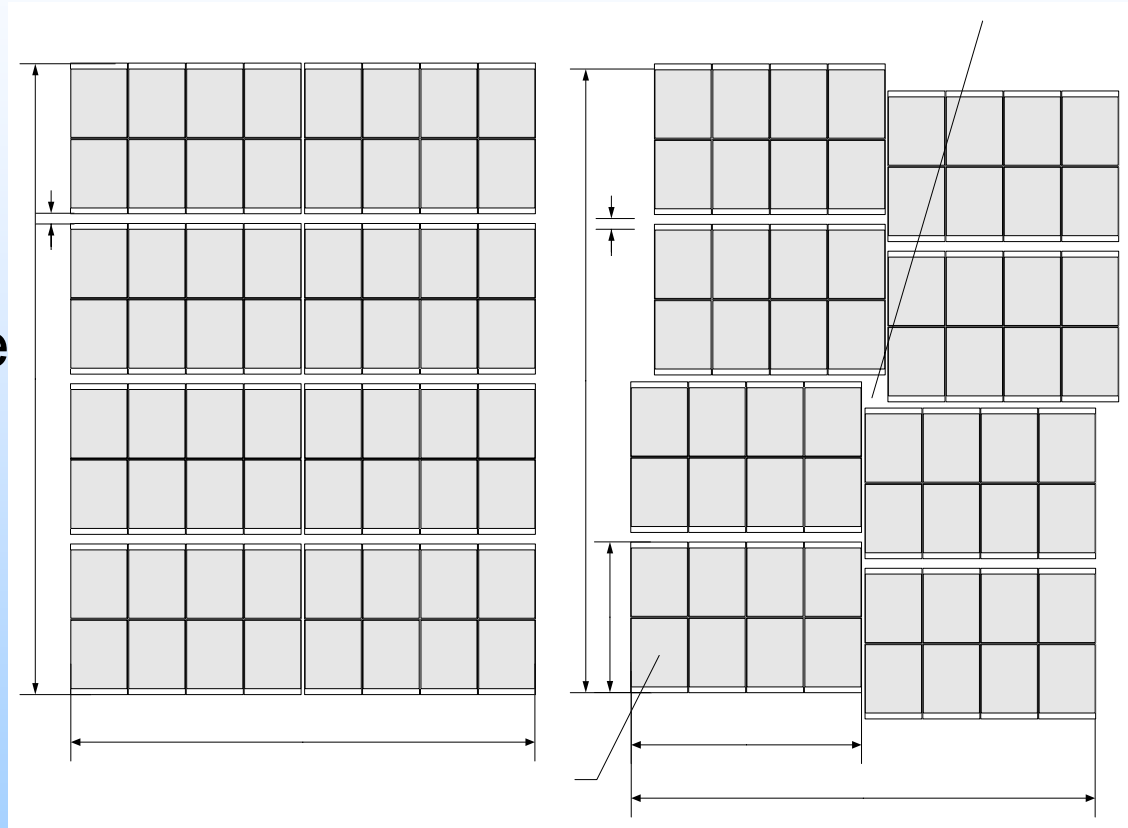
Programmable and flexible pipeline control (Off Chip):

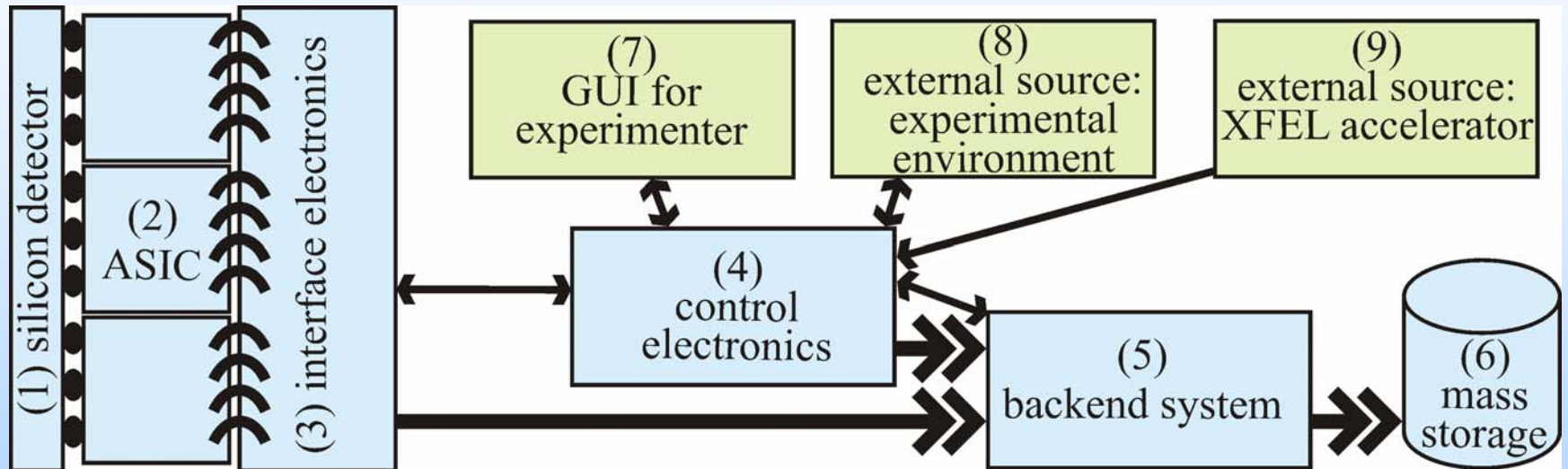
Number of X-ray pulses to be stored before readout (1, 10, or n-frames)

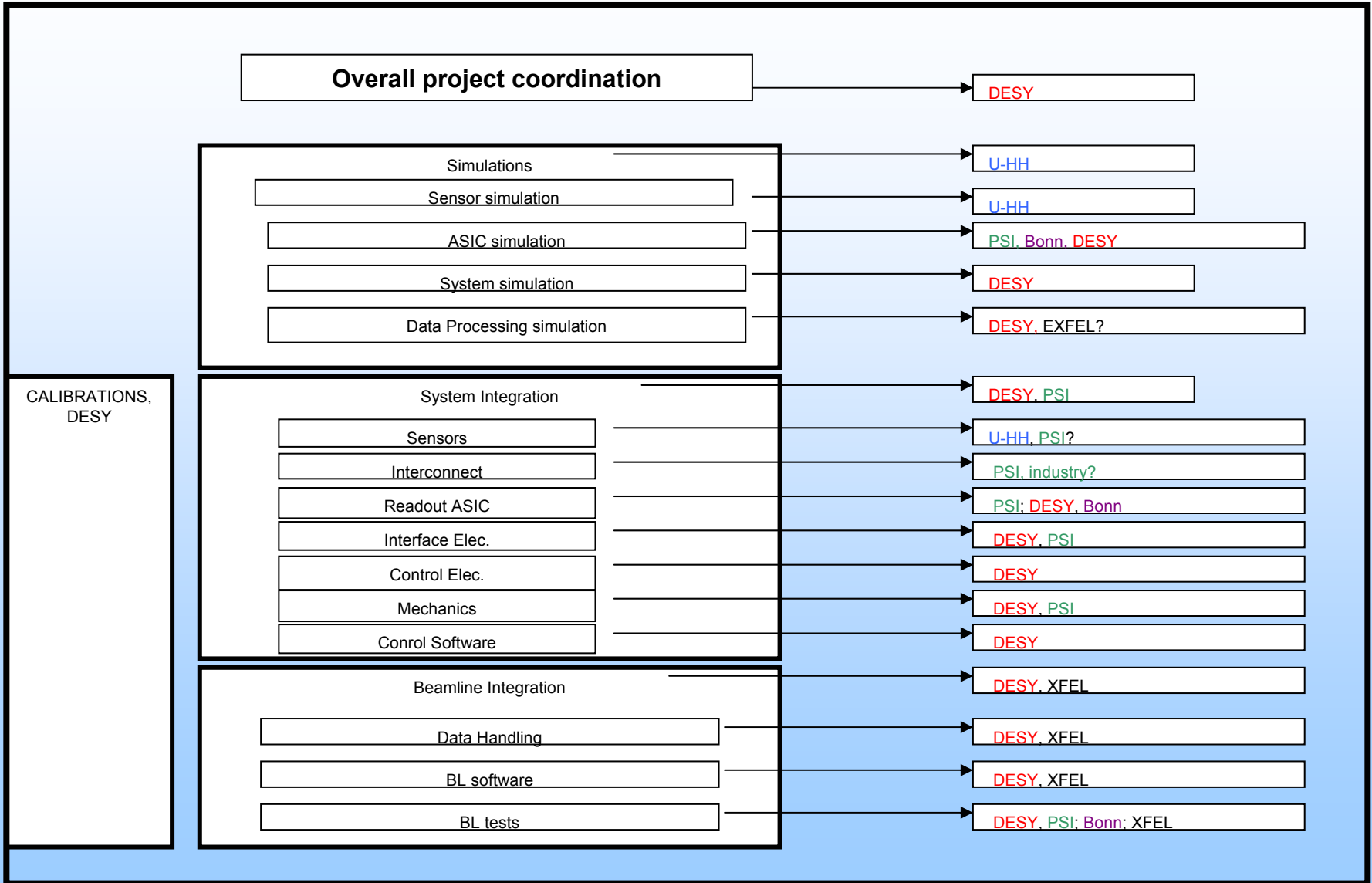
Adding of X-ray pulses (2 together, every 3rd pulse, ...)











Hybrid Pixel Detector (HPD) - Layout

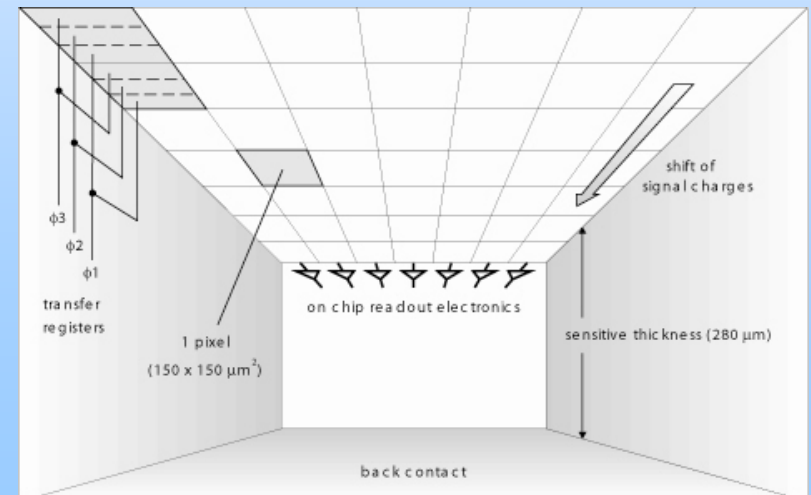
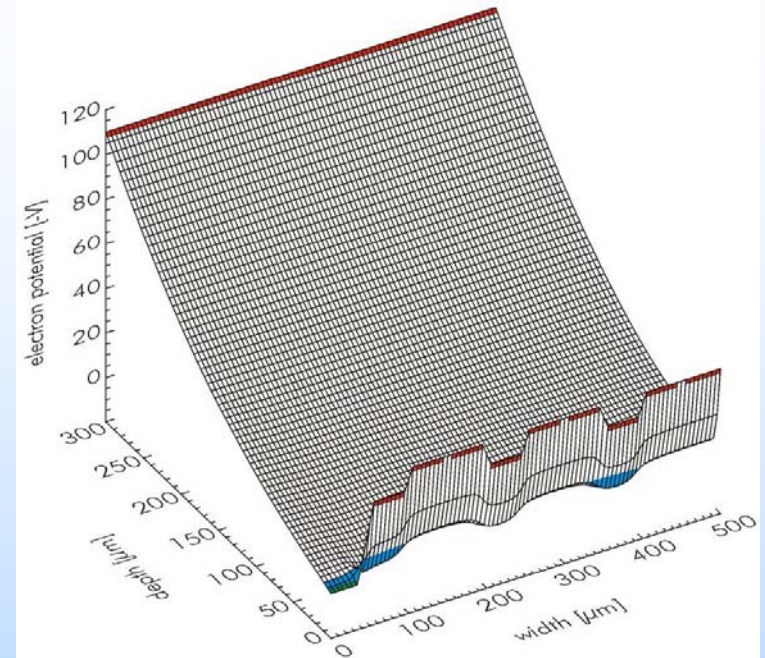
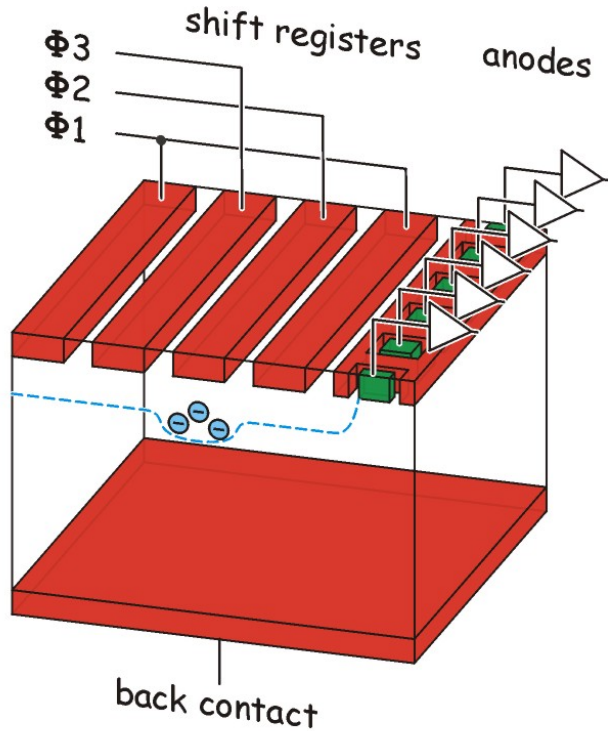
- Basic parameters:
- 100 micron pixels
- 5 MHz framing
- 400 frames storage
- 10^4 dynamic range
- 256 x 512 blocks
- 1k x 1k system
- Based on proven concepts



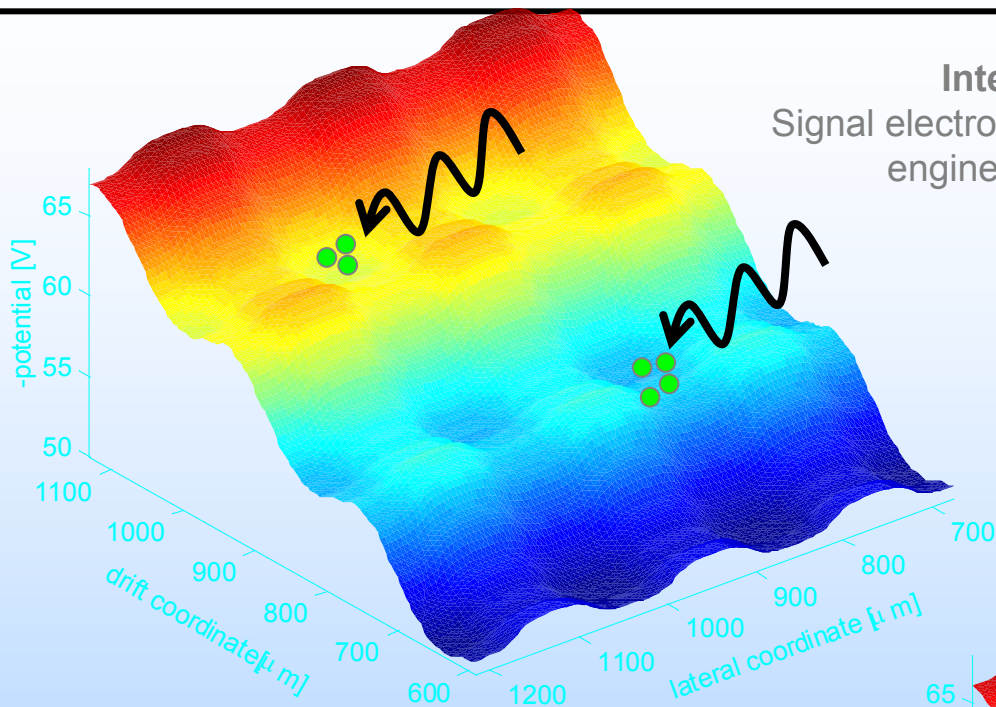




	2007	2008	2009	2010	2011	2012
Library						
Chip Design						
Mechanics						
Read Out Electronics						
Bump Bonding						
Module Prod						
Assembly						
Software (DAQ)						
Software Integ.						
Experim.						

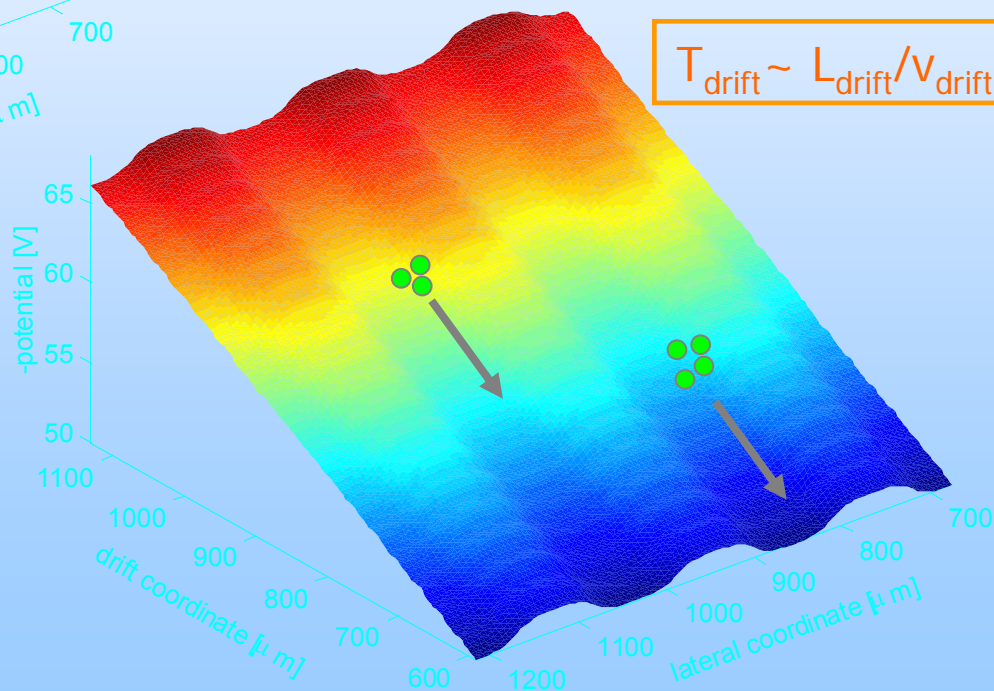


- full depletion (50 μm to 500 μm)
- back side illumination
- radiation hardness
- high readout speed
- pixel sizes from 30 μm to 1 mm
- charge handling: more than 10^6 e⁻/pixel
- high quantum efficiency



Integration phase:
Signal electrons are collected in suitably engineered potential wells

Readout phase:
A uniform drift field transports the electrons to the readout anodes in few μs.



Parameter settings

The following scenario is based on:

36 x 36 μm^2 pixel size

51 x 51 μm^2 pixel size

75 x 75 μm^2 pixel size up to 2k x 2k

100 x 100 μm^2 pixel size

Operating temperature: $\approx -10^\circ \text{C}$

Fabrication on high resistivity FZ silicon, 500 μm thick

Availability of chips

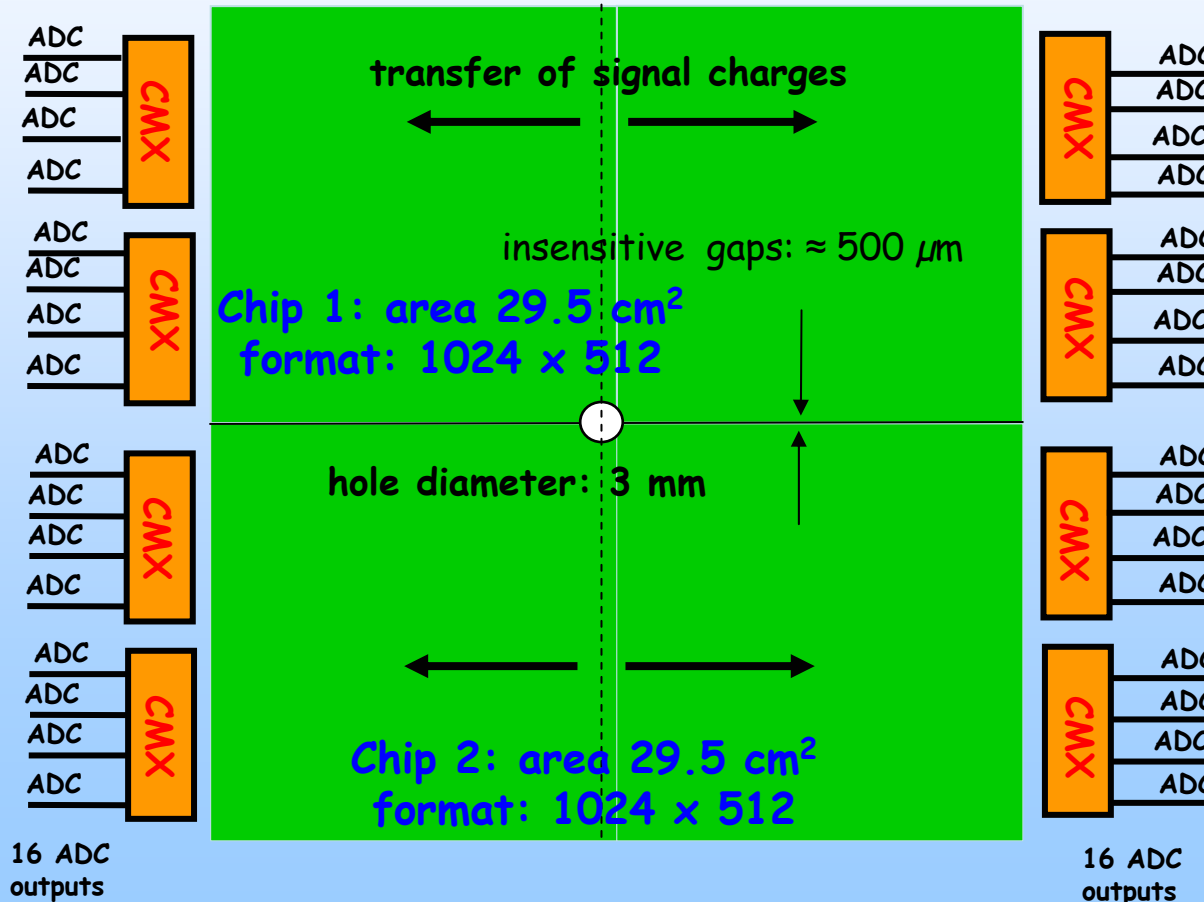
1. 256 x 512 is existing (2006)
2. 512 x 1024 actually fabricated, ready in early 2007
3. 1024 x 2048 end of fabrication in 2009/10

Availability of systems

add 2 years to get from a chip to a system

devices are in preparation[^], fabrication ready: mid. 2007

The full sensitive area of the system is 59 cm² with 75 μm pixels, 1024 x 1024



Full Frame imaging area per chip 512 x 1024

pixel size 75x75 μm²

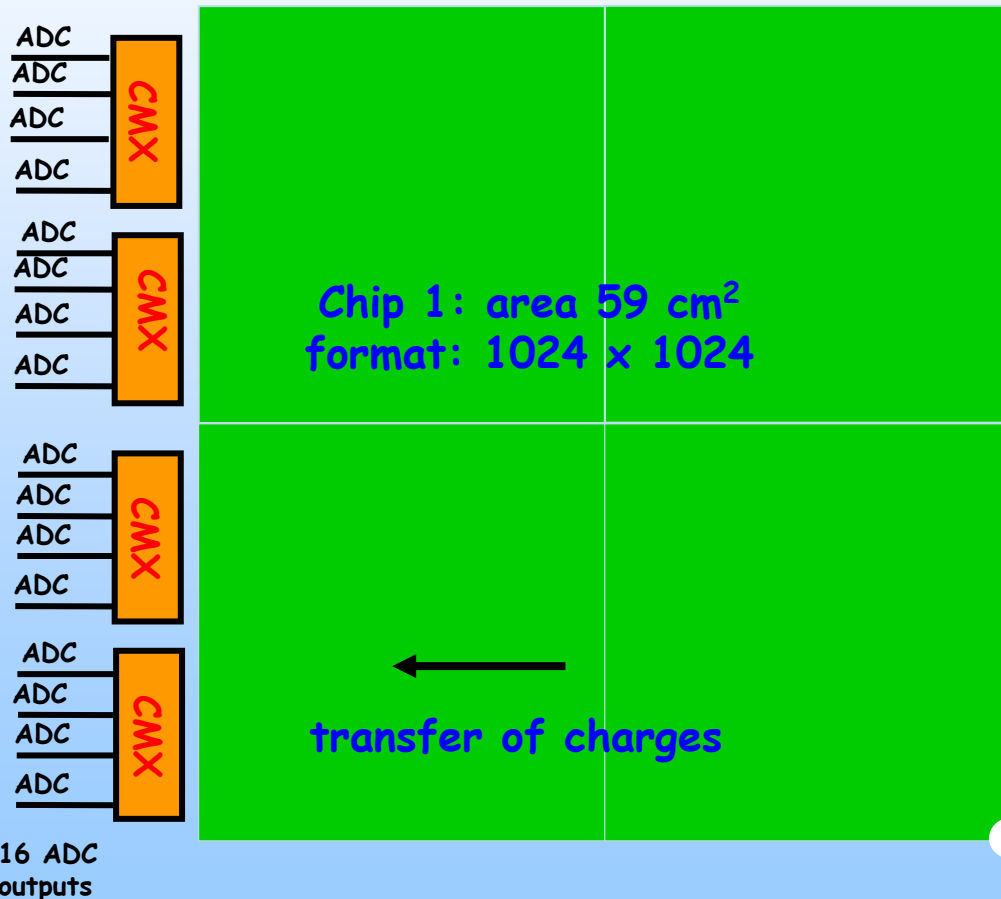
total area per chip: 29.5 cm²

readout time per frame: 4 ms i.e. 250 fps

Total sensitive system area: 59 cm²

devices are scheduled
for fabrication in 2009
ready: mid. 2010

The full sensitive area
of the system is 239 cm²
with 75 μm pixels, 2048 × 2048



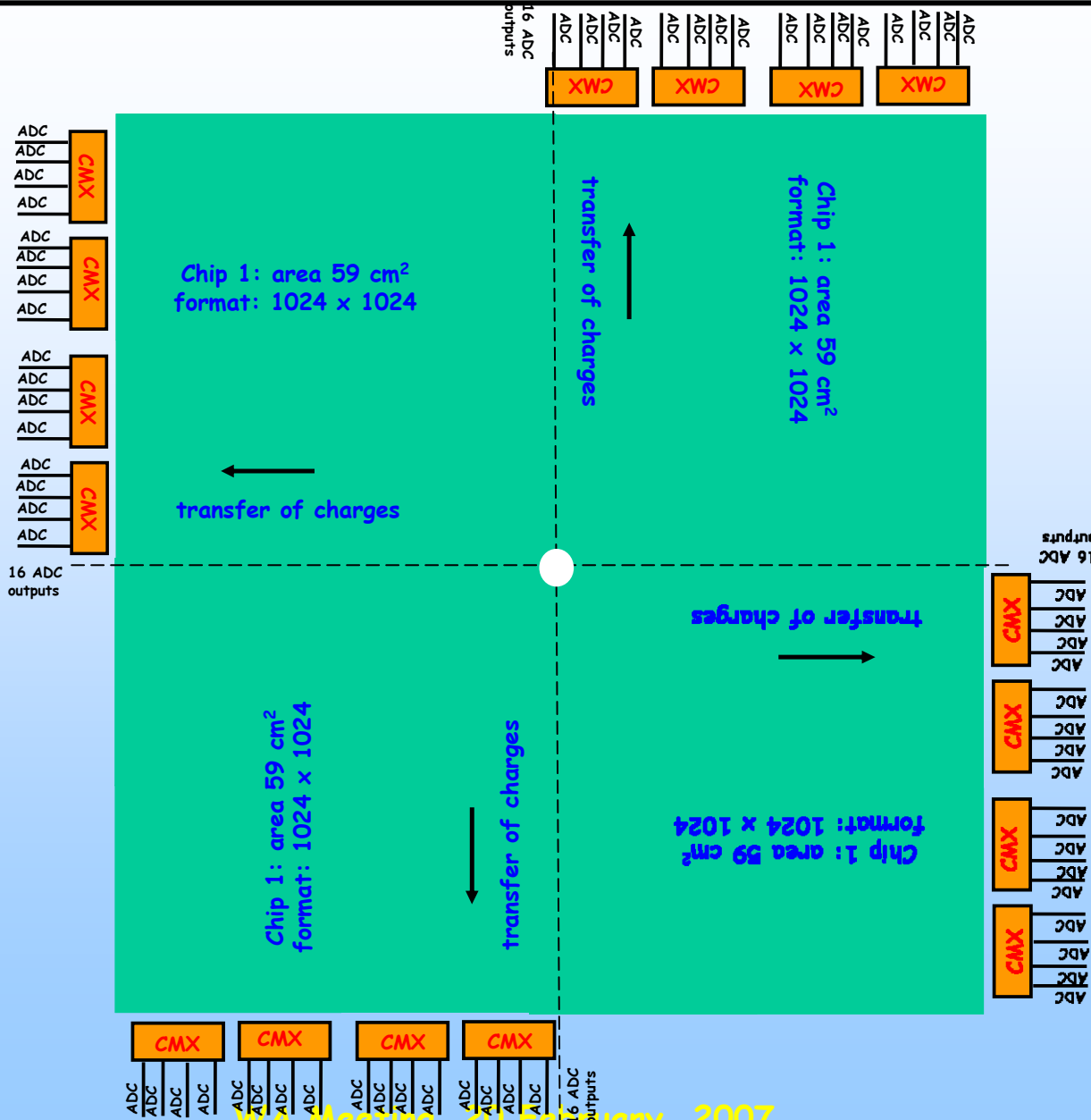
Full Frame imaging,
format per chip
1024 × 1024

pixel size
75x75 μm²

total area per chip:
59 cm², per system:
236 cm²

readout time per
frame: ≈ 8 ms
i.e. ≈ 125 fps

This system is 3 - side
butttable, can be extended to
a 2048 × 2048 array



2048 x 2048 CCD array

pixel size: 75 x 75 μm²

total area: 236 cm²

readout time: < 8 ms

read noise < 15 electrons

Charge handling capacity:
> 1000 photons pp

Energy 0.2 < E < 24 keV

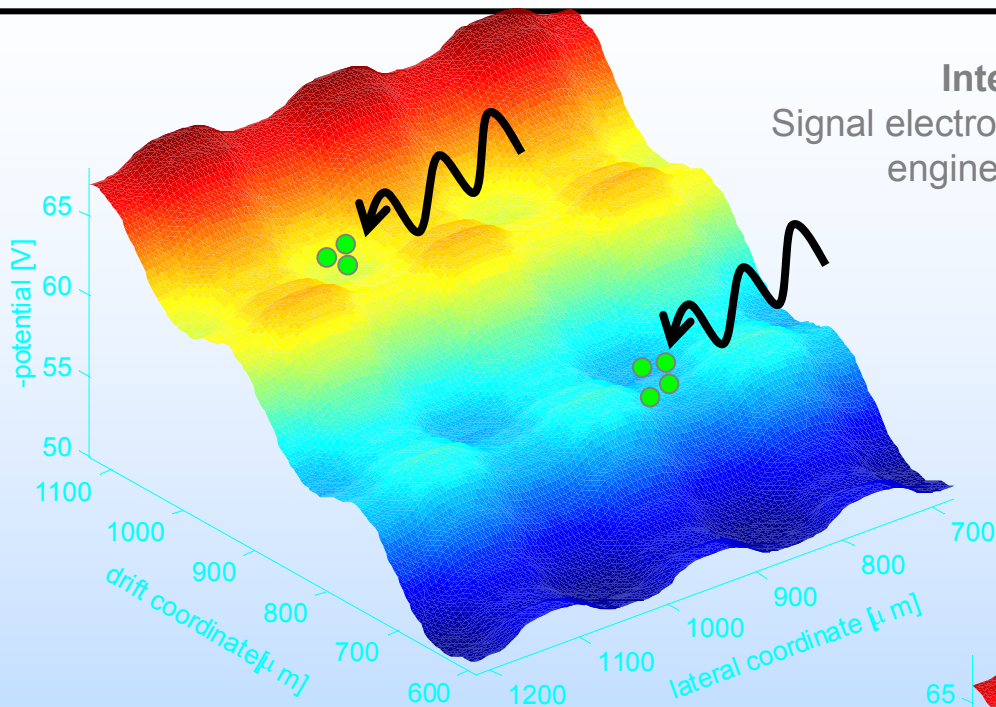
thickness: 500 μm

operation temperature: -10°C

Area detector I + II: pnCCD system (1k x 1k and 2k x 2k)

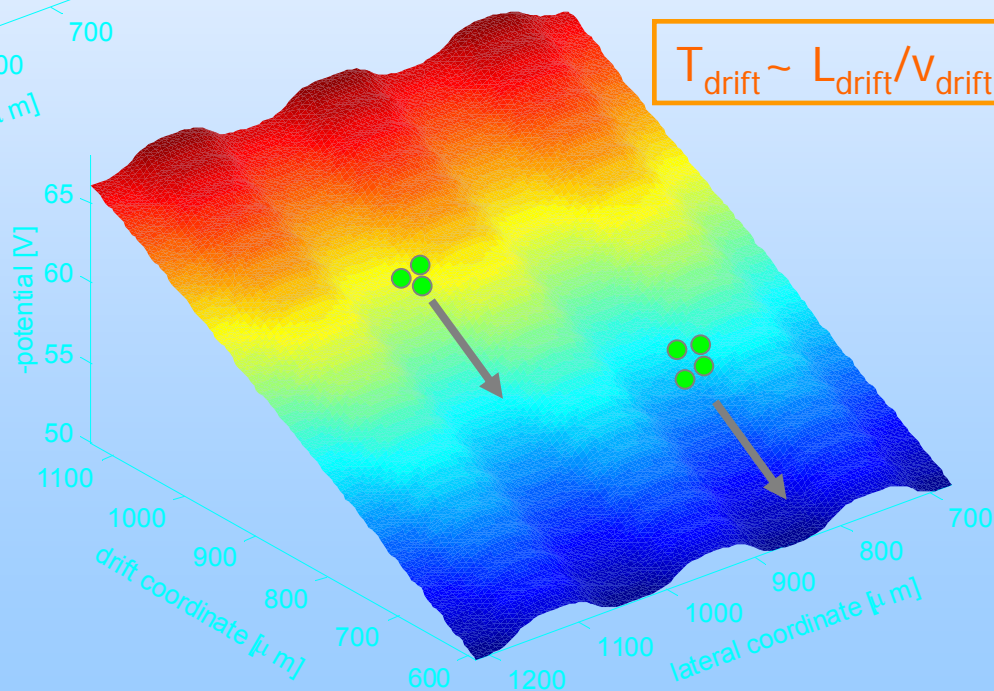
1. Detector development MPI HLL
 2. Front-end integrated analog electronics MPI HLL
 3. DAQ, slow control, mechanical and thermal integration, modelling MPI HLL, **DESY**
 4. Instrument and data analysis S/W, calibration (U.Siegen) + **DESY** + MPI HLL
- Estimated time for system I: 3 years (2009)
Estimated time for system II: 5 years (mid 2012)

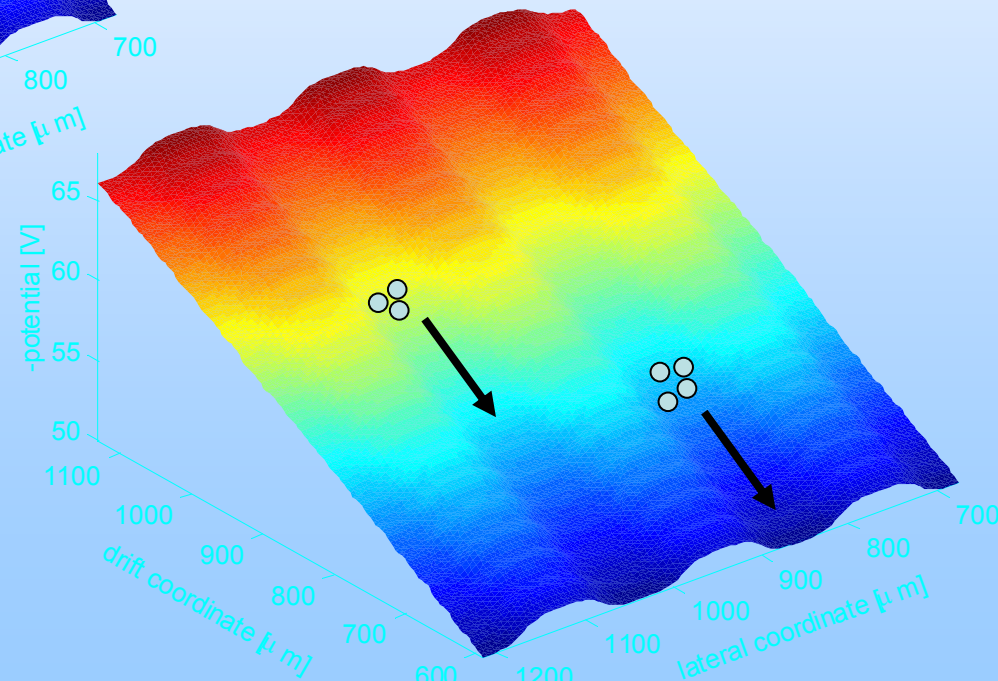
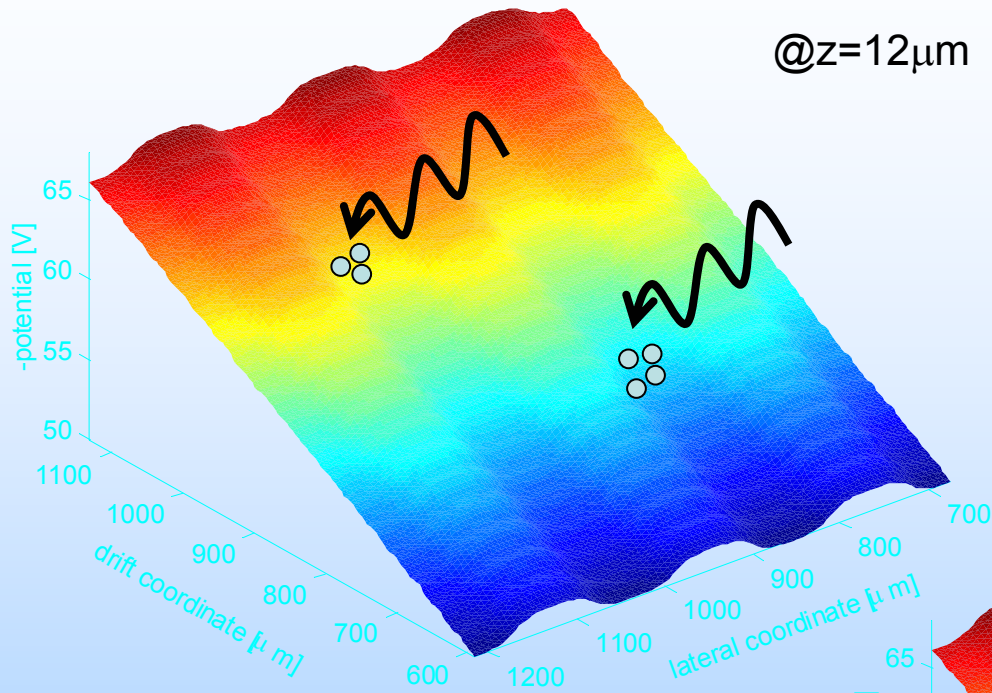
		2006 2. half			2007 1. half			2007 2. half			2008			2009		
1.	Project definition layout, fabrication	█	█	█	█	█	█	█								
2.	System concept, ASICs, PC boards, mechanical, thermal	█				█	█	█	█							
3.	Electrical tests, mounting, bonding,								█	█	█					
4.	System tests, qualification										█	█	█			
5.	Beamline tests @ DESY, LCLS implementation, test													█	█	█



Integration phase:
Signal electrons are collected in suitably engineered potential wells

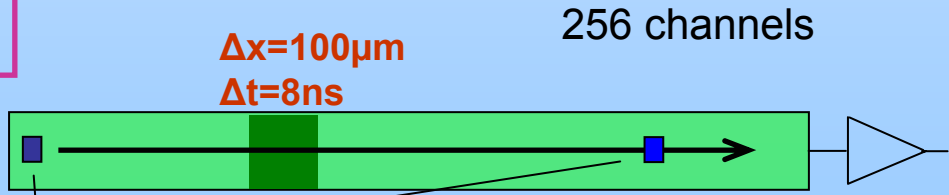
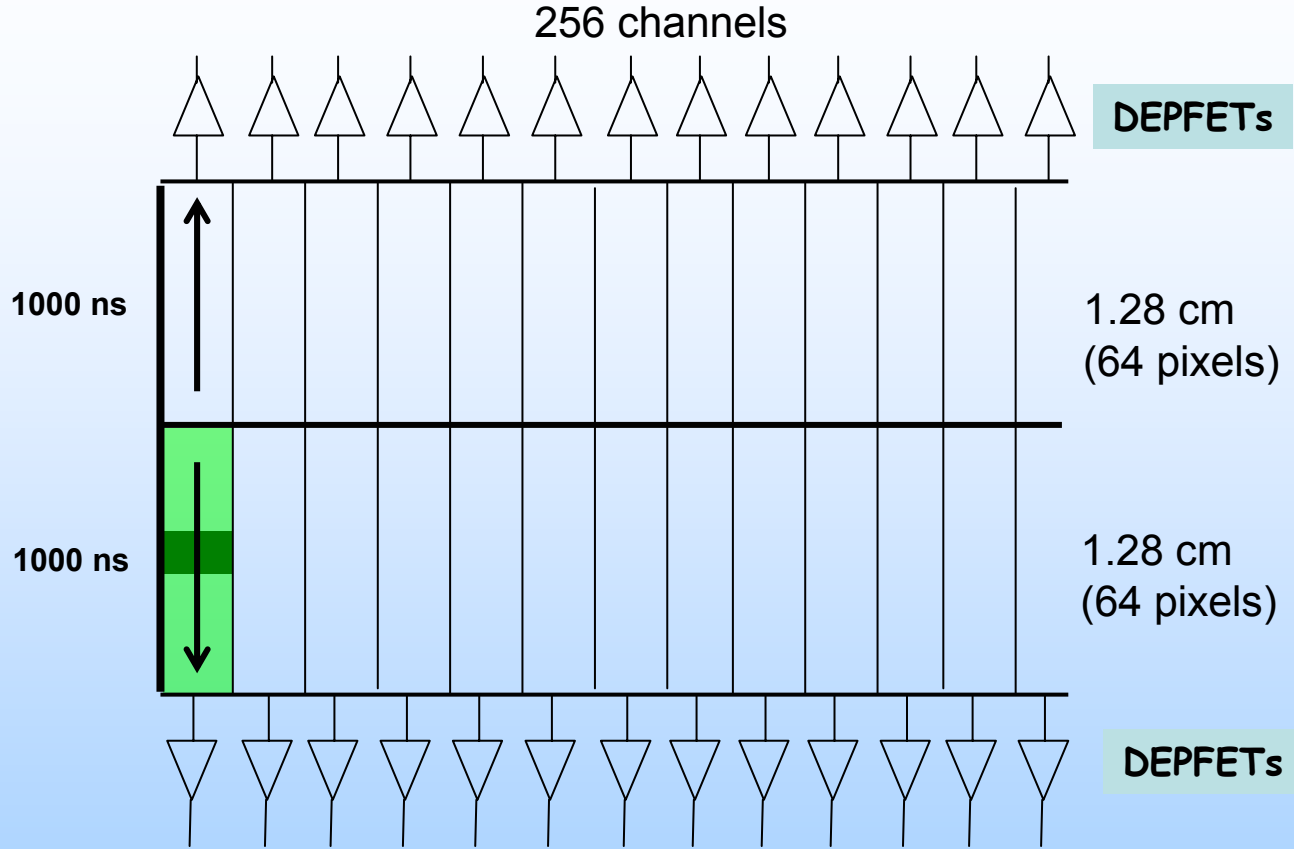
Readout phase:
A uniform drift field transports the electrons to the readout anodes in few μs.





The X-ray position along the drift is
obtained from the electrons' drift time
 $T_{\text{drift}} \sim 1000 \text{ ns} / 12.8 \text{ mm}$

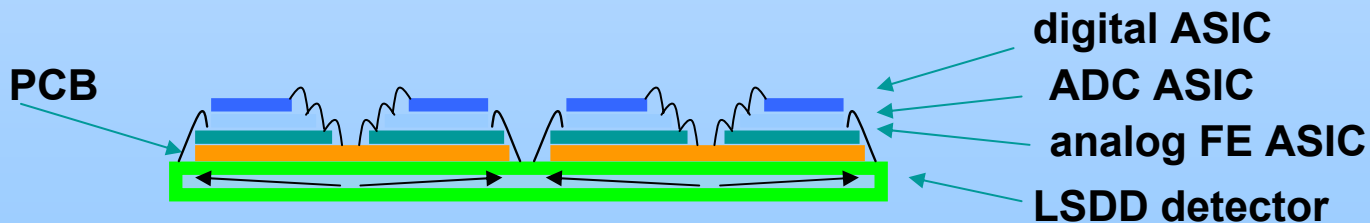
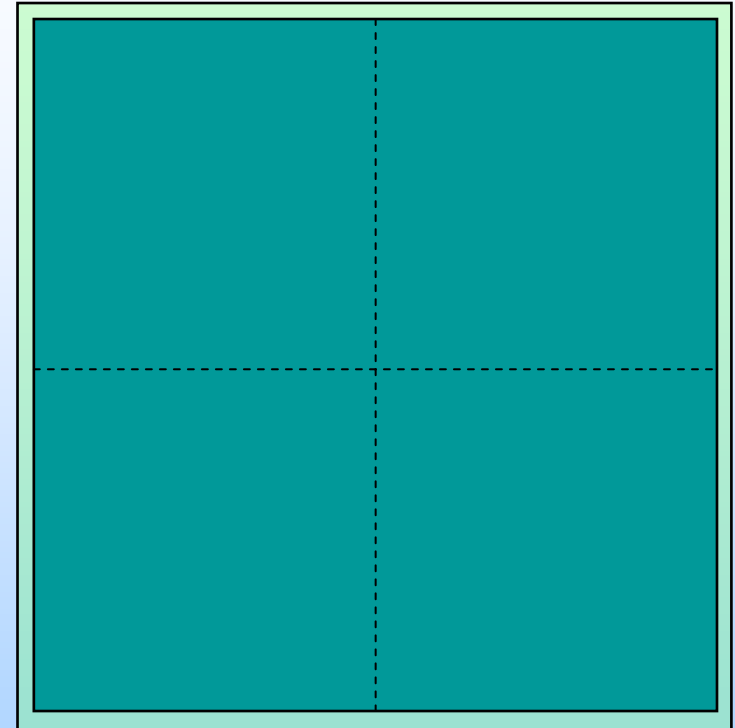
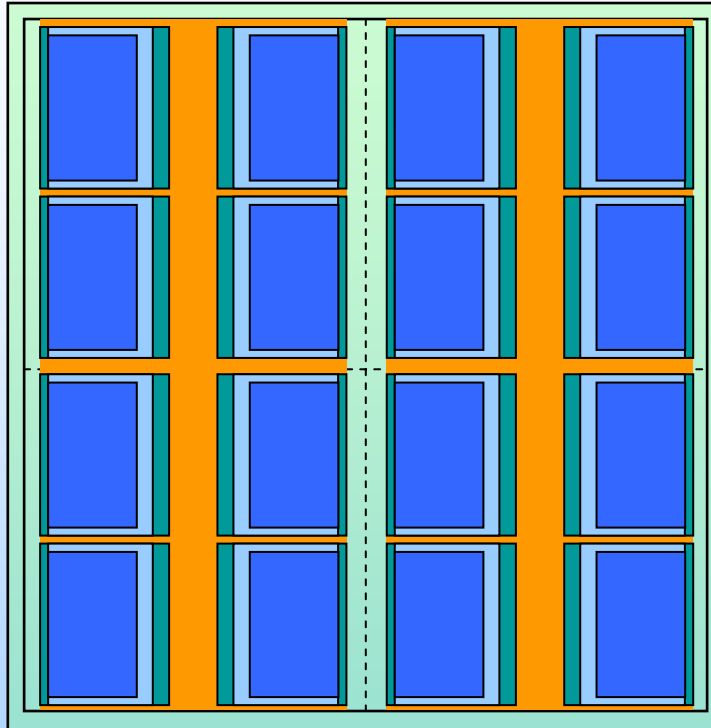
256x256
 2x256 channels
 1 MHz
 200 μ m pixel
 room temp.
 10³-10⁴ X-rays
 QE > 80% @ 10keV
 ENC < 30 el.
 Expandable to:
 512x512
 1024x1024
 (no dead area)

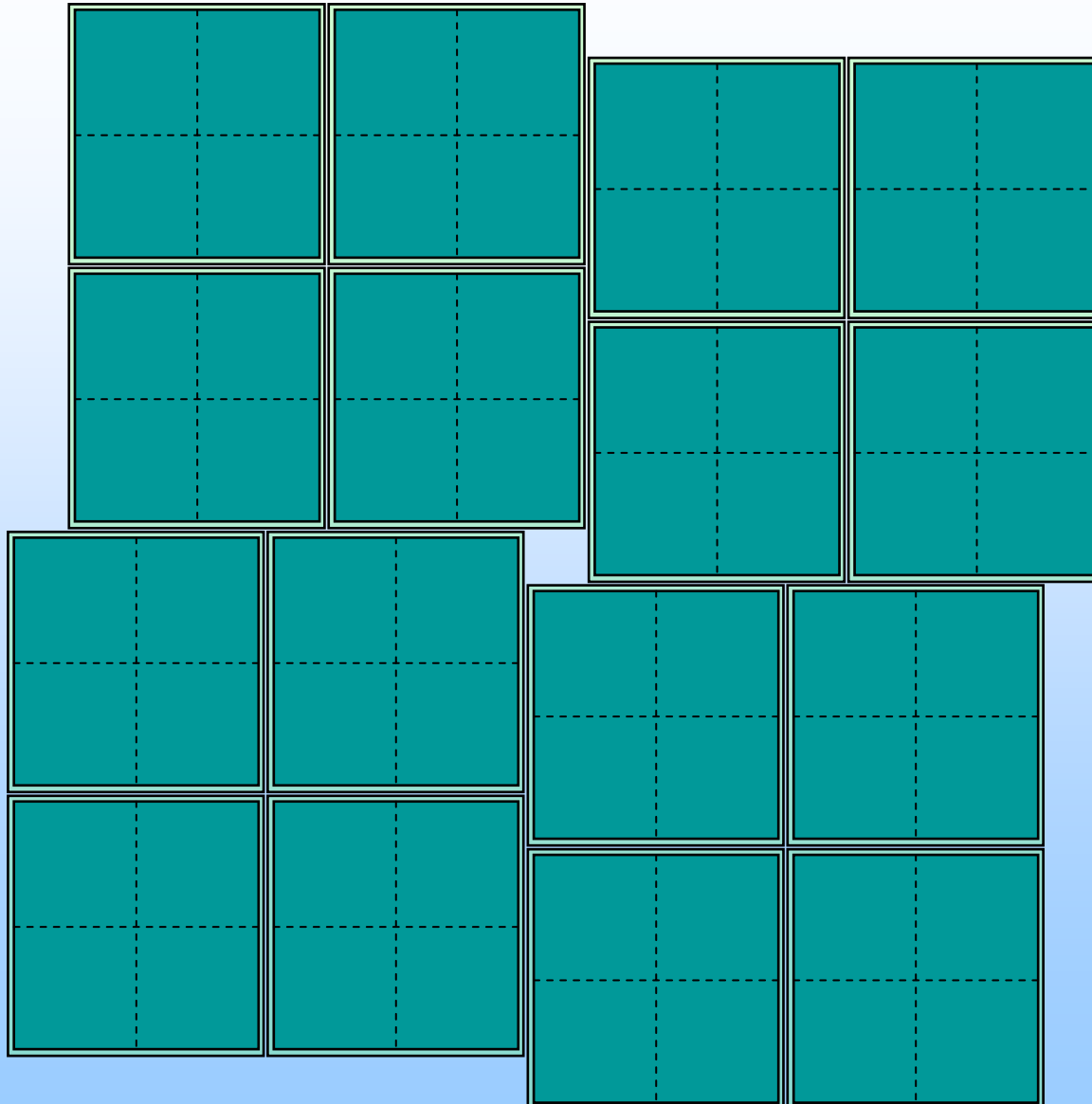


The final pixel size will be $100 \mu\text{m} < x < 200 \mu\text{m}$

drift velocity calibration with electron injectors

$V_{\text{drift}} \approx 13 \mu\text{m/ns}$ (i.e. $\sim 3.5\text{V}/30\mu\text{m}$ bias)
 $T_{\text{drift, max}} = 1000 \text{ ns}$





pixel size: **150 μ m - 200 μ m**

readout time
per frame: **1 μ s**

dead area
in FP: **13 %**

Readout
noise: **< 30 electrons**

max. number
of photons
per pixel: **10.000**

Energy
range: **0.5 keV - 25
keV**

Q.E.: **> 90 %**

final
format: **1024 \times 1024**

What is different from hybrid or CMOS pixel sensors?

An active area of $100 \times 12.800 \mu\text{m}^2$. (i.e. 128 pixels) is processed by one readout channel with an imaging pixel resolution of $100 \times 100 \mu\text{m}^2$.

this leads to:

reduced problems for interconnections

more ASIC area for signal processing

extremely low event thresholds

reduced power dissipation

„flexible“ pixel size, i.e. defined by time resolution

Advantages increase if the 5 MHz „dogma“ is relaxed

▶ XFEL case phase I (1 Mega frames per second) (3.5 yr)

detector and electronics must be expandable from 256x256 to 1024x1024

- ▶ sensor 256x256 with 100 μm pixel size
- ▶ frame rate
 - » Baseline: 500 kHz
 - » Goal: 1 MHz
- ▶ upgrade evaluation for >1 MHz operation
- ▶ threshold 1keV, counts/pixel/bunch 10^3 - 10^4 (10 keV) x-rays
- ▶ storage depth: from
 - » Baseline: 128 frames
 - » Goal: 512 frames

▶ detector and front end electronics fabrication with a synchrotron beam test at the end of study

(2010)

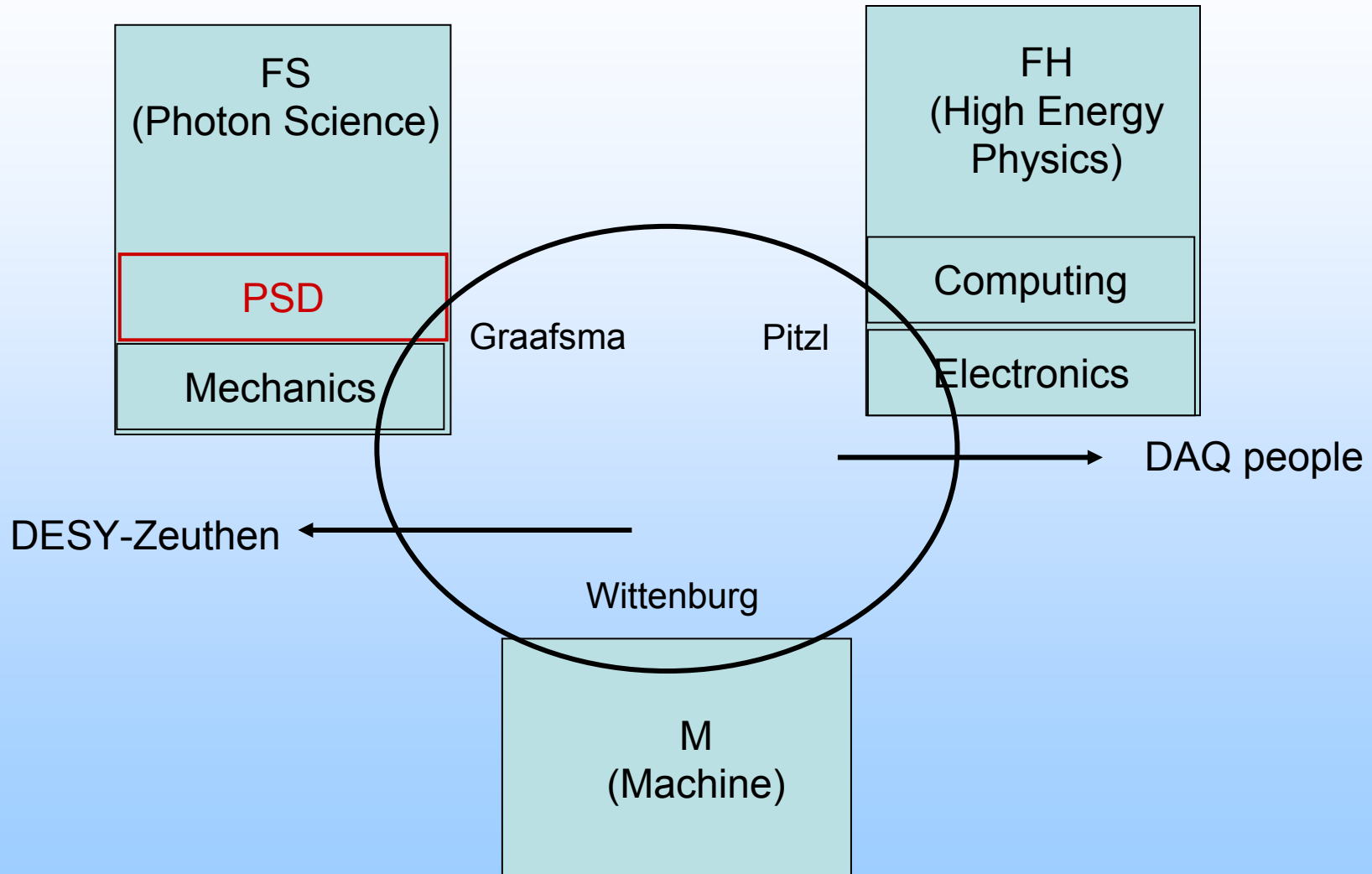
▶ XFEL case phase II (2 yr)

In 2011/2012 formats of 1024x1024 with 100 μm pixel operating at 1-5 MHz will be produced.



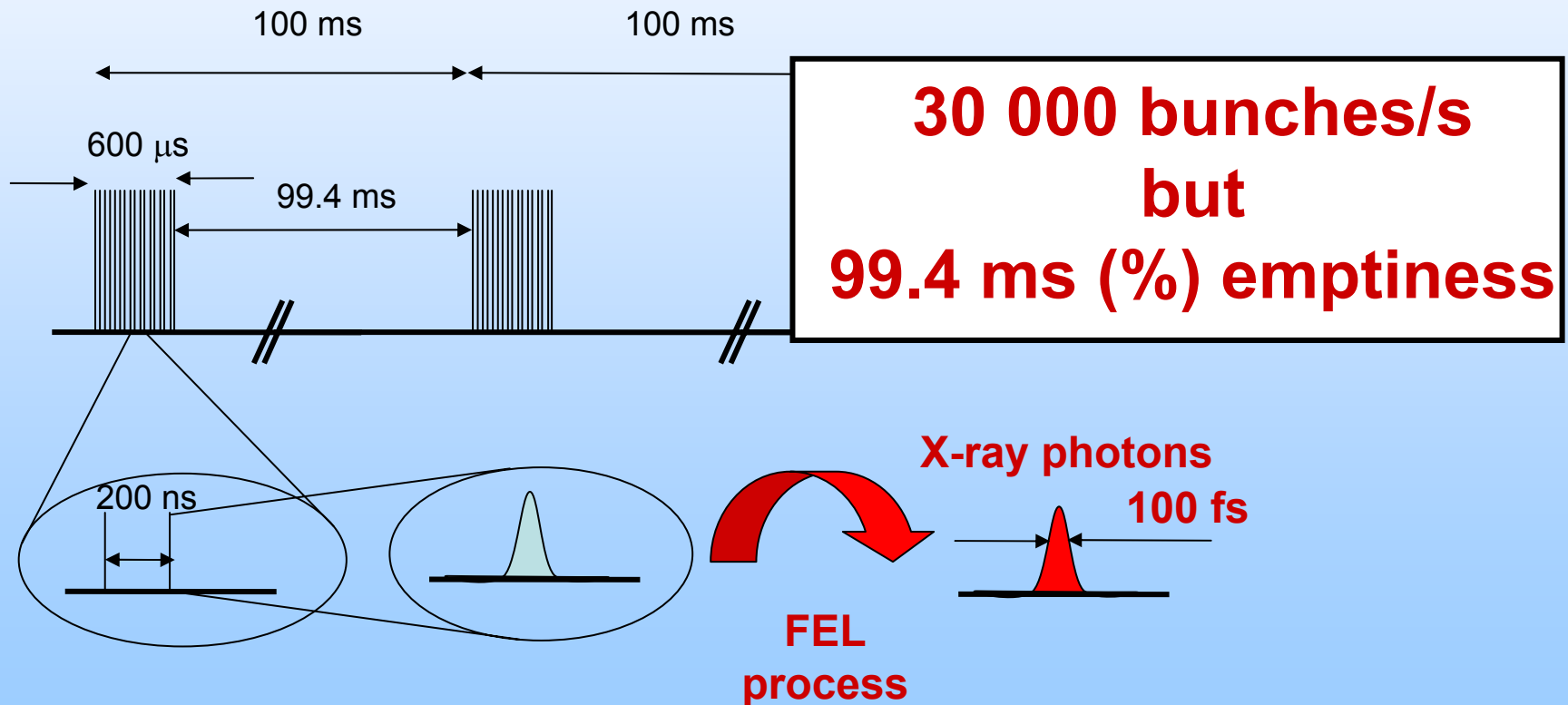
The European Consortium for high speed X-ray Imaging

		2006			2007			2008			2009			2010			2011			2012		
		1. half			2. half																	
1.	Project definition																					
2.	Proposal phase (Phase A)																					
3.	Selection phase (by XFEL GmbH)																					
4.	Project study Prototyping (Phase B & C)																					
5.	Imager fabrication (Phase D)																					



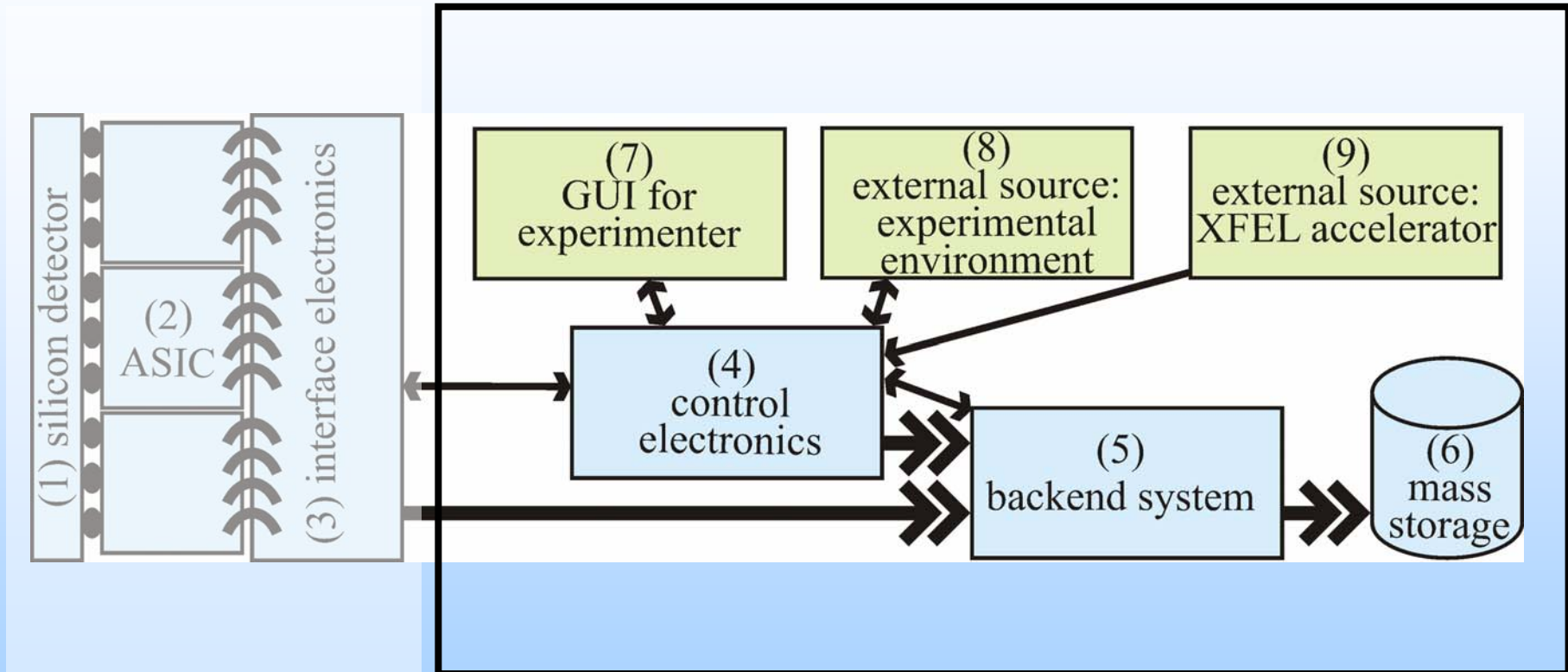
Time structure: difference with “others”

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Producing 100 fsec X-ray pulses (up to 30 000 bunches per second).



The Pilatus 6M Courtesy Christian Broennimann





DAQ

Summary:

- **Petra-III roadmap** advanced; detectors ordered and being tested
- **XFEL 2D detectors**
 - AP-HPAD: invited for proposal
 - LSDD: invited for proposal
 - pnCCD: invited for separate discussions
- Good and increasing **interaction** with **FE**
- Good and increasing **interaction** with **DAQ**
- DESY needs to strengthen **ASICs competence**
- Photon Science and HEP profit from **synergy**